



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

PATENT
Atty. Dkt. No. APPM/4471.Y1/CMP/ECP/RKK

Future Application of
Zheng, et al.

Serial No.: 09/614.407

Confirmation No.: 1903

Filed: July 12, 2000

For: Method of Application of Electrical Biasing To Enhance Metal Deposition

Commissioner for Patents
Washington, D.C. 20231

04/24/2003 WMITCHEL 00000001 200782 09614407

01 FC:1202 Dear Mr. CH

Group Art Unit: 1741

Examiner: E.D. Smith Hicks

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GROUP 1700

CERTIFICATE OF MAILING
37 CFR 1.8

I hereby certify that this correspondence is being deposited on April 14, 2003 with the United States Postal Service as First Class Mail in an envelope addressed to: Commissioner for Patents, Washington, D.C. 20231.

April 14, 2007

As Piannas

Signature

RESPONSE TO OFFICE ACTION DATED JANUARY 13, 2003

04/24/2003 WHITCHER 00000002 200782 09614407

01 FC:1201 420J88 response to the Office Action dated January 13, 2003, having a shortened statutory period for response set to expire on April 13, 2003, please enter this response and reconsider the claims pending in the application for reasons discussed below. Although Applicants believe that no fee is due in connection with this response, the Commissioner is hereby authorized to charge counsel's Deposit Account No. 20-0782/APPM/6671.Y1/AP, for any fees, including extension of time fees or excess claim fees, required to make this response timely and acceptable to the Office.

IN THE CLAIMS:

Please amend the claims as follows:

32. A method of depositing a metal on a substrate having one or more features formed thereon, comprising:

depositing a seed layer over the substrate and the one or more features;